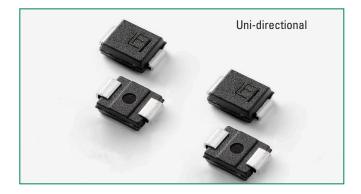


SMBJ-E Series







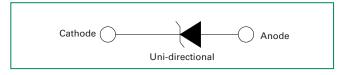


Maximum Ratings and Thermal Characteristics (T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation at T_A =25°C by 10/1000 μ s Waveform (Fig.2)(Note 1), (Note 2))	P _{PPM}	600	W
Power Dissipation on Infinite Heat Sink at T _L =50°C	P _D	5.0	W
Peak Forward Surge Current, 8.3ms Single Half Sine Wave (Note 3)	I _{FSM}	100	А
Maximum Instantaneous Forward Voltage at 50A for Unidirectional Only	V _F	3.5	V
Operating Temperature Range	T _J	-65 to 150	°C
Storage Temperature Range	T _{stg}	-65 to 175	°C
Typical Thermal Resistance Junction to Lead	R _{eJL}	20	°C/W
Typical Thermal Resistance Junction to Ambient	R _{eJA}	100	°C/W

- 1. Non-repetitive current pulse, per Fig. 4 and derated above T, (initial) =25°C per Fig. 3.
- 2. Mounted on copper pad area of 0.2x0.2" (5.0 x 5.0mm) to each terminal.
- 3. Measured on 8.3ms single half sine wave or equivalent square wave for unidirectional device only, duty cycle=4 per minute maximum.

Functional Diagram



Description

The SMBJ-E series is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events.

Features

- Excellent clamping capability
- Low incremental surge resistance
- For surface mounted applications to optimize board space
- Low profile package
- Typical failure mode is short from over-specified voltage or current
- Whisker test is conducted based on JEDEC JESD201A per its table 4a and 4c
- IEC-61000-4-2 ESD 30kV(Air), 30kV (Contact)
- ESD protection of data lines in accordance with IEC 61000-4-2
- EFT protection of data lines in accordance with IEC 61000-4-4
- Built-in strain relief
- Fast response time: typically less than 1.0ps from 0V to BV min

- 600W peak pulse power capability at 10/1000us waveform, repetition rate (duty cycles):0.01%
- High temperature to reflow soldering guaranteed: 260°C/40sec
- V_{BB} @ T_J = V_{BB}@25°C $\times (1 + \alpha T \times (T_1 - 25))$ (a T:Temperature Coefficient, typical value is 0.1%)
- EPI silicon technology
- Meet MSL level1, per J-STD-020C, LF maximun peak of 260°C
- Matte tin lead-free plated
- Halogen free and RoHS compliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)

Applications

TVS devices are ideal for the protection of I/O Interfaces, V_{cc} bus and other vulnerable circuits used in Telecom, Computer, Industrial and Consumer electronic applications.

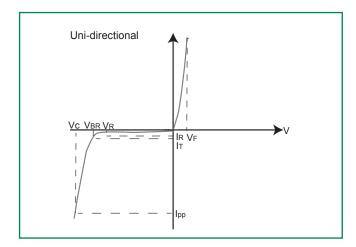
TVS Diodes Surface Mount – 600W > SMBJ-E Series

Electrical Characteristics (T_a=25°C unless otherwise noted)

Number Marking Stan		Reverse Stand off Voltage V _R	f Voltage V _{BR}		Test Current I _T	Maximum Clamping Voltage V _c @	Maximum Peak Pulse Current I _{pp}	Maximum Reverse Leakage I _R @ V _R
(2111)		(Volts)	MIN	MAX	(mA)	(V)	(A) **	(μΑ)
SMBJ300A-E	YE	300	335.0	371.0	1	486.0	1.30	1
SMBJ350A-E	YG	350	391.0	432.0	1	567.0	1.10	1
SMBJ400A-E*	YK	400	447.0	494.0	1	648.0	0.93	1
SMBJ440A-E*	YM	440	492.0	543.0	1	713.0	0.85	1
SMBJ500A-E*	YN	500	558.0	618.0	1	810.0	0.75	1
SMBJ550A-E*	YP	550	614.0	680.0	1	891.0	0.67	1
SMBJ600A-E*	YR	600	670.0	741.0	1	971.0	0.62	1
SMBJ650A-E*	YS	650	726.0	803.0	1	1052.0	0.57	1
SMBJ700A-E*	YT	700	782.0	865.0	1	1133.0	0.53	1
SMBJ750A-E*	YU	750	837.0	927.0	1	1213.0	0.50	1
SMBJ850A-E*	YV	850	950.0	1050.0	1	1365.0	0.44	1

Note: for parts with * are still under development

I-V Curve Characteristics



- $\mathbf{P}_{_{\mathbf{PPM}}}$ Peak Pulse Power Dissipation Max power dissipation
- $V_{_{R}}$ Stand-off Voltage Maximum voltage that can be applied to the TVS without operation
- V_{ss} Breakdown Voltage Maximum voltage that flows though the TVS at a specified test current (I,)
- **V**_ε **Clamping Voltage** Peak voltage measured across the TVS at a specified Ippm (peak impulse current)
- I_{R} Reverse Leakage Current -- Current measured at V_{R}
- $\mathbf{V}_{_{\mathrm{F}}}$ Forward Voltage Drop for Uni-directional



Ratings and Characteristic Curves (T_a=25°C unless otherwise noted)

Figure 1 - TVS Transients Clamping Waveform

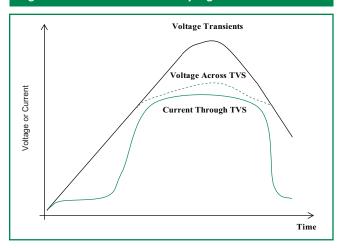


Figure 2 - Peak Pulse Power Rating

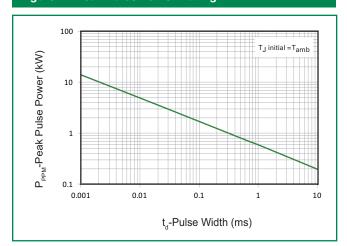


Figure 3 - Peak Pulse Power Derating Curve

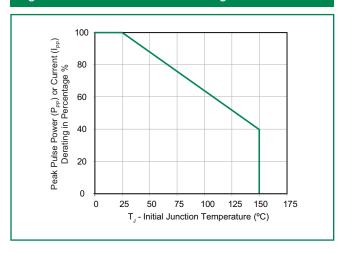


Figure 4 - Pulse Waveform

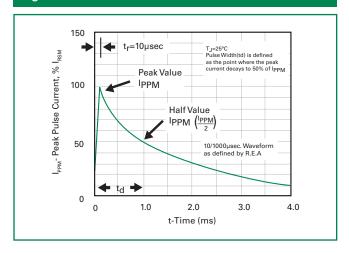


Figure 5 - Typical Junction Capacitance

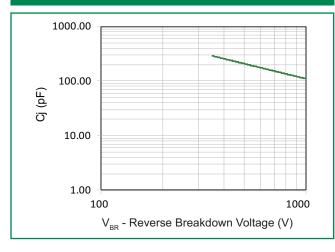


Figure 6 - Typical Transient Thermal Impedance

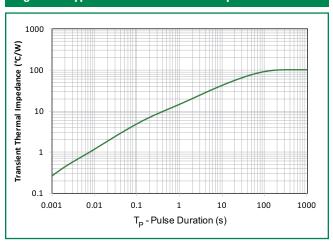




Figure 7 - Maximum Non-Repetitive Peak Forward Surge Current Uni-Directional Only

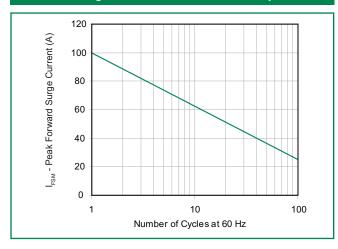
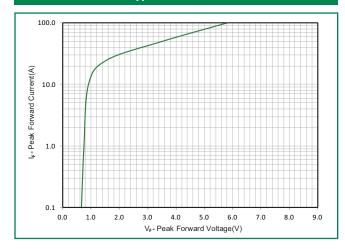


Figure 8 - Peak Forward Voltage Drop vs Peak Forward Current (Typical Values)

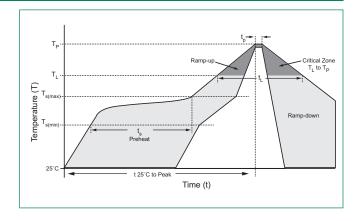


Soldering Parameters

Reflow Co	ndition	Lead-free assembly	
	-Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (min to max) (t _s)	60 – 180 secs	
Average ra to peak	mp up rate (Liquidus Temp (T _A)	3°C/second max	
T _{S(max)} to T _A	- Ramp-up Rate	3°C/second max	
Reflow	-Temperature (T _A) (Liquidus)	217°C	
nellow	-Time (min to max) (t _s)	60 - 150 seconds	
Peak Temp	erature (T _P)	260+ ^{0/-5} °C	
Time withi Temperatu	n 5°C of actual peak re (t _p)	20 - 40 seconds	
Ramp-dow	n Rate	6°C/second max	
Time 25°C	to peak Temperature (T _P)	8 minutes Max.	
Do not exc	eed	260°C	



Weight	0.003 ounce, 0.093 grams		
Case	JEDEC DO214AA. Molded plastic body over glass passivated junction		
Polarity	Color band denotes cathode except Bidirectional		
Terminal	Matte Tin-plated leads, Solderable per JESD22-B102		



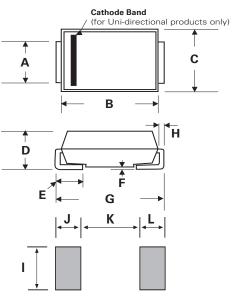
Environmental Specifications

High Temp. Storage	JESD22-A103
нткв	JESD22-A108
Temperature Cycling	JESD22-A104
MSL	JEDEC-J-STD-020, Level 1
H3TRB	JESD22-A101
RSH	JESD22-A111



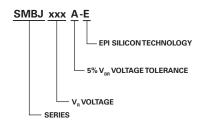
Dimensions

DO-214AA (SMB J-Bend)



Dimensions	Incl	nes	Millimeters		
Dimensions	Min	Max	Min	Max	
А	0.076	0.086	1.930	2.200	
В	0.160	0.187	4.060	4.750	
С	0.130	0.155	3.300	3.940	
D	0.078	0.103	1.990	2.610	
E	0.030	0.060	0.760	1.520	
F	-	0.008	-	0.203	
G	0.205	0.220	5.210	5.590	
Н	0.006	0.012	0.152	0.305	
1	0.089	-	2.260	-	
J	0.085	-	2.160	-	
K	-	0.107	-	2.740	
L	0.085	-	2.160	-	

Part Numbering System



Part Marking System



Packaging

Part number	Component Package	Quantity	Packaging Option	Packaging Specification
SMBJxxxA-E	DO-214AA	3000	Tape & Reel - 12mm tape/13" reel	EIA STD RS-481

Tape and Reel Specification

